

● **WLP-12-01 Power Dissipation (JESD51-7)**

Power dissipation data for the WLP-12-01 is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as one of reference data taken in the described condition.

1. Measurement Condition (Reference data)

Condition : Mount on a board

Ambient : Natural convection

Soldering : Lead (Pb) free

Board : The board using 4 copper layer.

(76.2mm × 114.3mm •••Area: about 8700mm²)

1st layer : No copper foil (Signal layer)

2nd layer : 70mm×70mm_Connected to heat-sink.

3rd layer : 70mm×70mm_Connected to heat-sink.

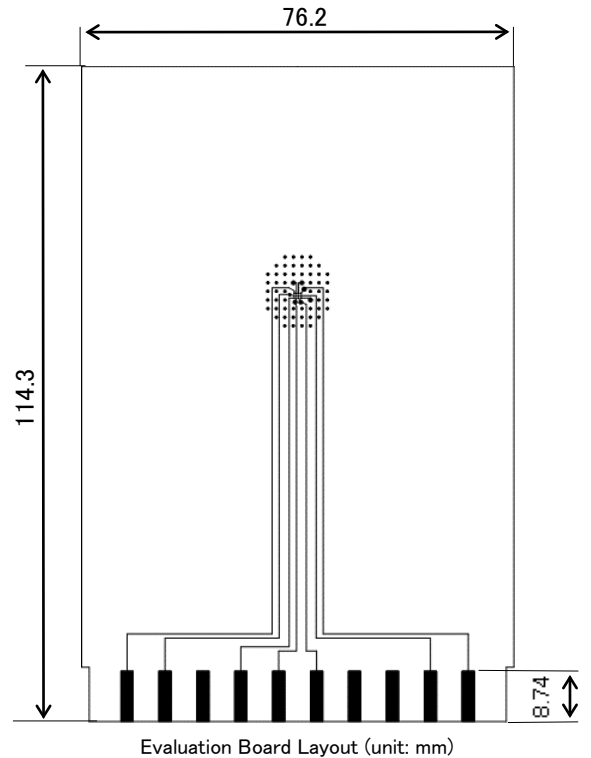
4th layer : No copper foil (Signal layer)

Material : Glass Epoxy (FR-4)

Thickness : 1.6mm

Through-hole : φ 0.2mm x 60pcs

Copper foil Thickness: 1st ,4th layer 70um , 2nd ,3rd layer 35um



2. Power Dissipation vs. Ambient temperature

Board Mount(T_{jmax} = 125°C)

Ambient Temperature(°C)	Power Dissipation Pd(mW)		θ _a (°C/W)
	T _a max=85°C	T _a max=105°C	
25	890	890	112.36
85	356	356	
105	0	178	
125	0	0	

